

F

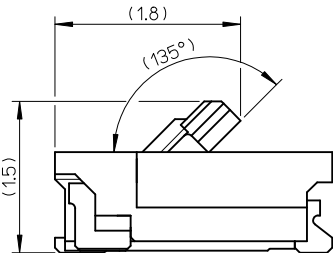
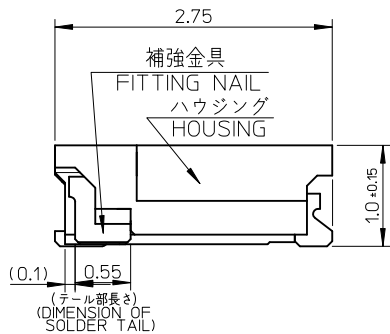
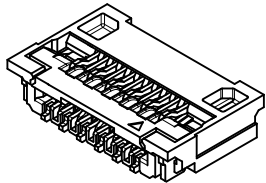
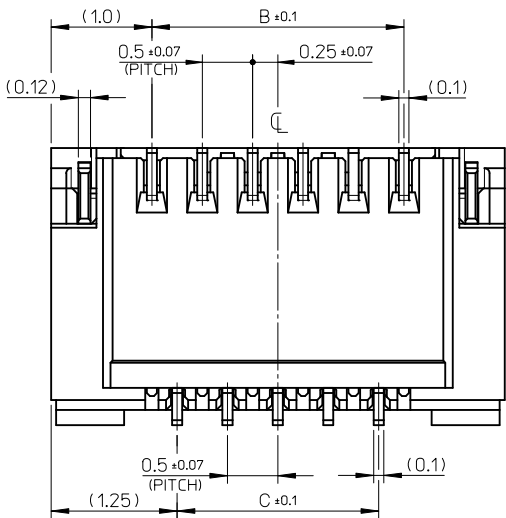
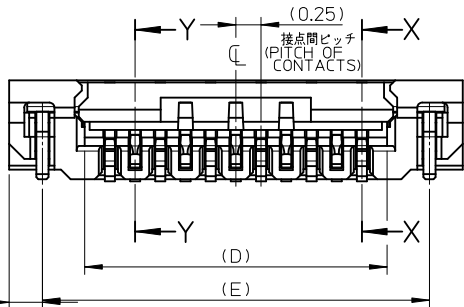
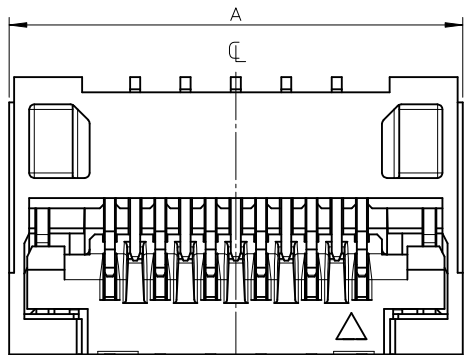
E

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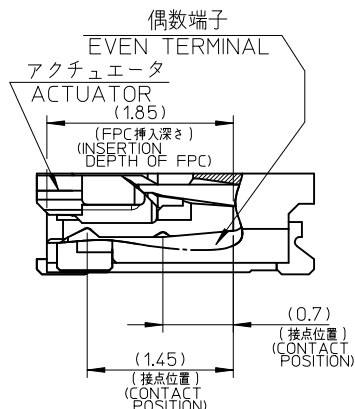
C

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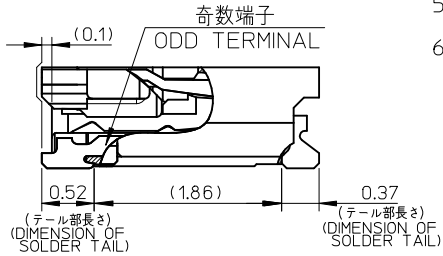
A



アクチュエータ開放位置
ACTUATOR OPENING POSITION



SECTION Y-Y



SECTION X-X

注記 NOTES

- 使用材料 MATERIALS
ハウジング : 耐熱性樹脂(UL94V-0、ベージュ)
アクチュエータ : 耐熱性樹脂(UL94HB、黒色)
奇数端子 : 銅合金、ニッケル下地、金メッキ
偶数端子 : 銅合金、ニッケル下地、金メッキ
補強金具 : 銅合金、ニッケル下地、スズメッキ
HOUSING : G.F. HEAT RESISTANCE PLASTIC (BEIGE)
ACTUATOR : G.F. HEAT RESISTANCE PLASTIC (BLACK)
ODD TERMINAL : COPPER ALLOY, Gold OVER Nickel PLATING
EVEN TERMINAL : COPPER ALLOY, Gold OVER Nickel PLATING
FITTING NAIL : COPPER ALLOY, Tin OVER Nickel PLATING
- 端子、補強金具のコプラナリティーは 0.1 以下とする
COPLANALITY OF SOLDER TAILS AND FITTING NAILS : 0.1MAX.
- 一般公差 : ± 0.3
GENERAL TOLERANCES: ±0.3
- アクチュエータの図示箇所にゲート逃の凹みがつきます
THERE ARE DENT SHAPES AT ACTUATOR FOR MOLDING GATE
- ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT
- 塩素系・臭素系難燃剤非使用
CHLORINATED AND BROMINATED FLAME RETARDANTS FREE

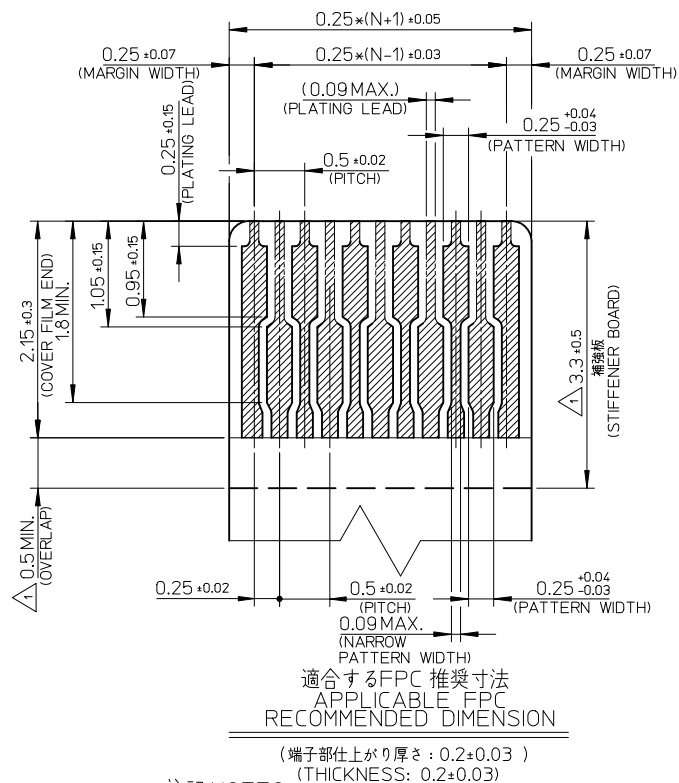
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9.34	8.5	7.5	8	10	502078-3310	502078-3318	33
7.34	6.5	5.5	6	8	502078-2510	502078-2518	25
6.34	5.5	4.5	5	7	502078-2110	502078-2118	21
5.34	4.5	3.5	4	6	502078-1710	502078-1718	17
E	D	C	B	A	ORDER NO.	MATERIAL NO.	CKT.=N

502078-**-18 MODEL NO.

REVISED EC NO: J2012-0409 DRAWN: TANAKA 2011/09/21 CHKD: 2011/09/30 APPR: SHOSHIKAWA 2011/09/30 REV B	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY YFUJITA	DATE 2008/12/15	TITLE 0.25 PITCH FPC CONN E/O HGT=1.0 BTM CONTACT TYPE				
		10 OVER 30 UNDER	± ---	CHECKED BY TKANEKO	DATE 2008/12/15					
		30 OVER	± ---	APPROVED BY AHORINO	DATE 2008/12/15	MOLEX MOLEX INCORPORATED				
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.				SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-502078-003				1 OF 2
REV		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

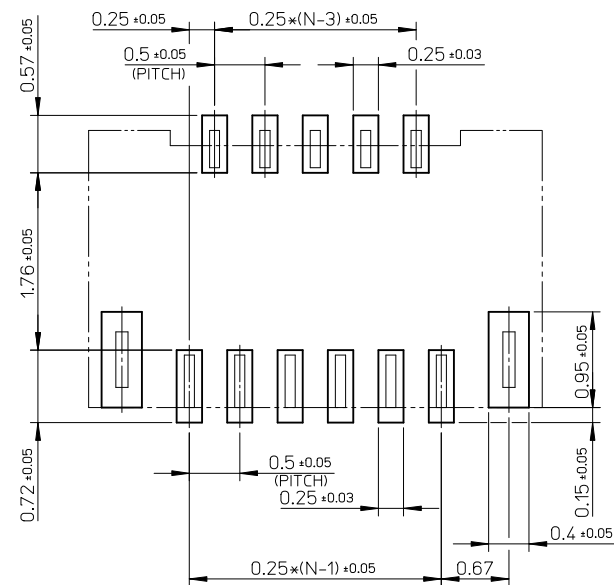
FPC構成材料例

EXAMPLE OF FPC
COMPOSITION MATERIAL



注記 NOTES

- ① 補強板長さが図面通り確保できない場合は、カバーレイと補強板のオーバーラップ法を 0.5mm 以上としてください
WHEN STIFFENER BOARD DIMENSION CAN NOT
BE SECURE AS DRAWING, PLEASE GIVE THE OVERLAP
SIZE OF COVER FILM AND STIFFENER BOARD AS
0.5mm MINIMUM
- 2 推奨ペースト厚 : 100 μ m
推奨マスク開口率 : 80%
RECOMMEND SCREEN THICKNESS : 100 μ m
RECOMMEND SCREEN OPEN RATIO : 80%



FPC 挿入側
FPC INSERTION SIDE
参考基板レイアウト
RECOMMENDED PCB
PATTERN DIMENSIONS (REF.)

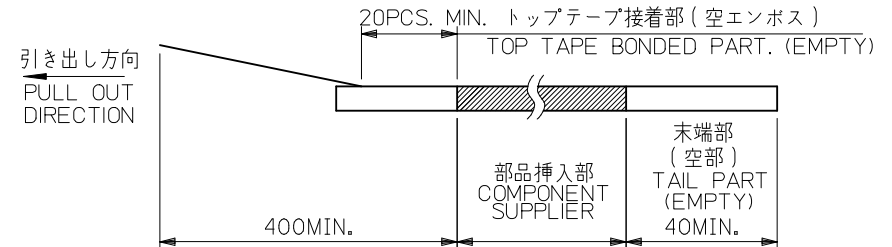
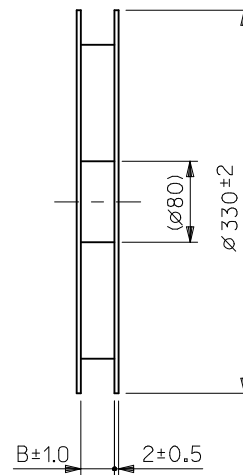
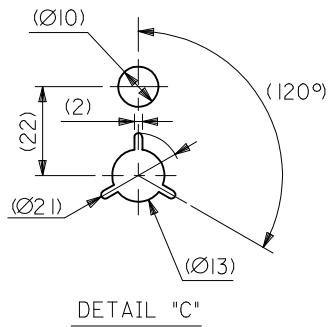
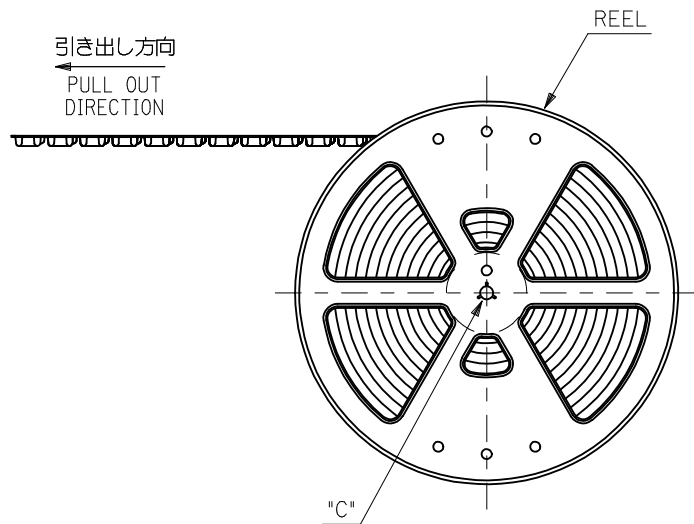
- ③ FPCパターンのメッキ仕様は
金メッキ：0.14μm以上
下地ニッケルメッキ：2~6μm
FPC PATTERN PLATING
GOLD PLATING：0.14μm MINIMUM
NICKEL UNDER PLATING：2~6μm

- 4 FPCについて (ABOUT FPC)
- 抜き方向は、導体側から補強板側を推奨します
補強板材質は、ポリイミドを推奨します
接着剤は熱硬化接着剤を推奨します
なお、接着剤の接点部への付着は導通不良の原因となりますので染み出しがないよう、お願いします
- RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BORAD SIDE
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY

REVISED EC NO.: J2012-0409 DRAWN: MTANAKA CHKD: APPR: SHOSHIKAWA 2011/09/21 2011/09/30	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY YFUJITA	DATE 2008/12/15	TITLE 0.25 PITCH FPC CONN E/O HGT=1.0 BTM CONTACT TYPE			
		10 OVER 30 UNDER	± ---	CHECKED BY TKANEKO	DATE 2008/12/15				
		30 OVER	± ---	APPROVED BY AHORINO	DATE 2008/12/15	 MOLEX INCORPORATED			
		ANGULAR	±1 °	MATERIAL NO.					
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE SHEET 1 OF 2		SD-502078-003		2 OF 2		
SIZE A3			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

注記 NOTES

- 製品詳細寸法については図面 SD-502078-003 を参照下さい。
RE DETAILED DIMENSION, SEE SD-502078-003
- 梱包数量 : 3000 個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- 材料 MATERIAL
キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE) : PET , PE , PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

RELEASED EC NO.: J2009-1529 DRWN: YFUJITA 2008/12/15 CHKD: TKANEKO 2008/12/15 APPR: TKANEKO 2008/12/15	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	MODEL NO. 502078-**-10	THIRD ANGLE PROJECTION
		10 UNDER ± 0.2		DRAWN BY DATE YFUJITA 2008/12/15		TITLE 0.25 FPC CONN E/O HSG ASSY EMBOSSED TAPE PACKAGE MOLEX INCORPORATED		
		10 OVER 30 UNDER ± 0.25		CHECKED BY DATE TKANEKO 2008/12/15				
		30 OVER ± 0.3		APPROVED BY DATE AHORINO 2008/12/15				
	ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-502078-004		1 OF 2	
	REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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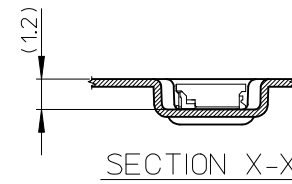
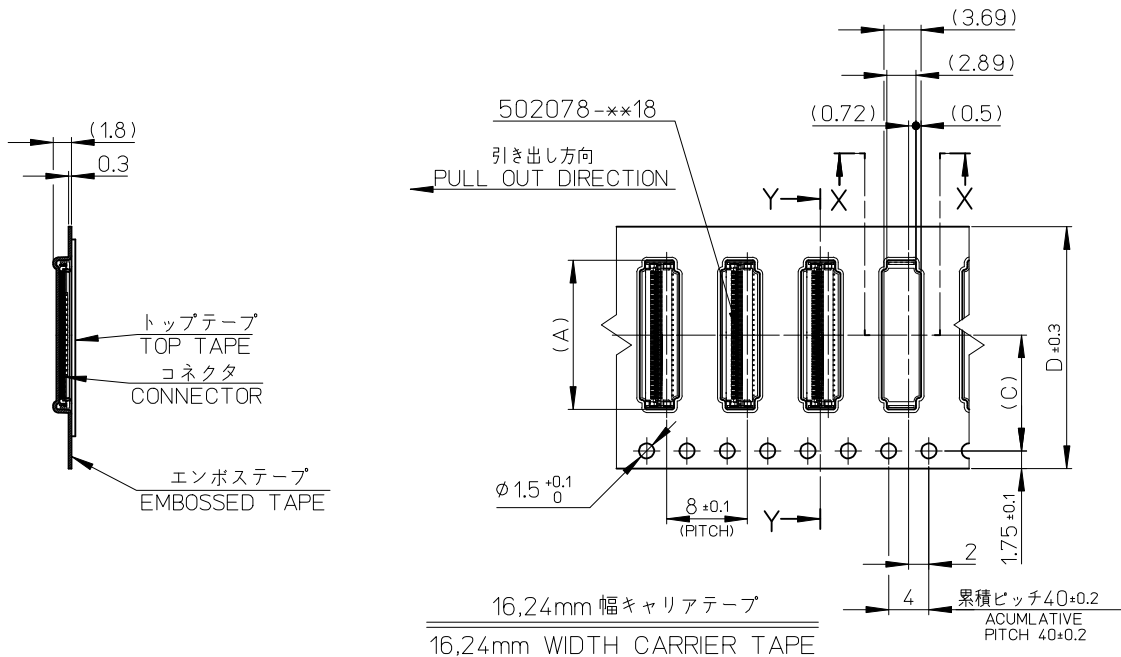
E

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24	11.5	25.4	14.8	502078-5110	51
			11.8	502078-3910	39
			10.3	502078-3310	33
			8.3	502078-2510	25
			7.3	502078-2110	21
16	7.5	17.4	6.3	502078-1710	17
D キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	製品番号 MATERIAL NO.	極数 CKT.
MODEL NO.			502078-**10		
DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC		 THIRD ANGLE PROJECTION
DRAWN BY DATE FUJITA 2008/12/15		TITLE 0.25MM FPC CONN E/O HSG ASSY EMBOSSD TAPE PACKAGE			
CHECKED BY DATE YANEKO 2008/12/15					
APPROVED BY DATE MORINO 2008/12/15		 MOLEX INCORPORATED			
MATERIAL NO. SEE CHART					
DOCUMENT NO. SD-502078-004		SHEET NO. 2 OF 2			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

RELEASED EC NO: J2009-1529 DRWN:YFUJITA CHKD:TKANEKO APPR:TKANEKO REV O	DESCRIPTION 2008/12/15 2008/12/15 2008/12/15	GENERAL TOLERANCES (UNLESS SPECIFIED)	
		10 UNDER	± 0.2
		10 OVER 30 UNDER	± 0.25
		30 OVER	± 0.3
		ANGULAR ±1 °	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

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В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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